



IGBT Modules

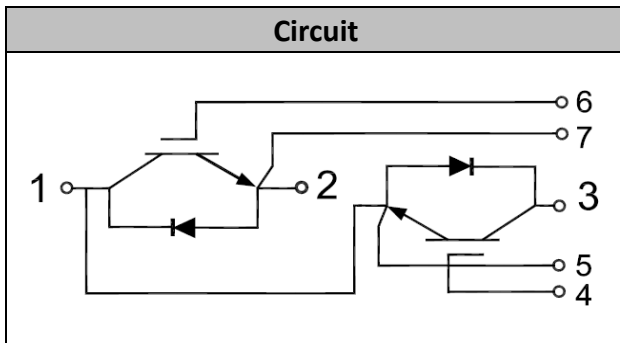
V_{CES}	1200V
I_c	300A

Applications

- Motion/sevo control
- High frequency switching application
- UPS (Uninterruptible Power Supplies)
- Welding machine

Features

- Low $V_{ce(sat)}$ with Trench technology
- Low switching losses especially Eoff
- $V_{ce(sat)}$ with positive temperature coefficient
- High short circuit capability(10us)
- Including ultra fast & soft recovery anti-parallel FWD
- Low inductance package
- Maximum junction temperature 175°C



● IGBT

Absolute Maximum Ratings

Parameter	Symbol	Conditions	Value	Unit
Collector-Emitter Voltage	V_{CES}	$V_{GE}=0V, I_c = 1mA, T_{vj}=25^{\circ}C$	1200	V
Continuous Collector Current	I_c	$T_c=100^{\circ}C$	300	A
Repetitive Peak Collector Current	I_{CRM}	$tp=1ms$	600	A
Gate-Emitter Voltage	V_{GES}	$T_{vj}=25^{\circ}C$	± 20	V
Total Power Dissipation	P_{tot}	$T_c=25^{\circ}C$ $T_{vjmax}=175^{\circ}C$	1700	W

**Characteristic values**

Parameter	Symbol	Conditions	Value			Unit	
			Min.	Typ.	Max.		
Gate-emitter Threshold Voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=8mA, T_{vj}=25^{\circ}C$	5.2	5.8	6.4	V	
Collector-Emitter Cut-off Current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V, T_{vj}=25^{\circ}C$			1.0	mA	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=300A, V_{GE}=15V, T_{vj}=25^{\circ}C$		2.25	2.70	V	
		$I_C=300A, V_{GE}=15V, T_{vj}=125^{\circ}C$		2.55			
Gate Charge	Q_G			2.3		uC	
Input Capacitance	C_{ies}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz, T_{vj}=25^{\circ}C$		14.2		nF	
Reverse Transfer Capacitance	C_{res}				0.8		nF
Gate-Emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V, T_{vj}=25^{\circ}C$			400	nA	
Turn-on Delay Time	$t_{d(on)}$	$I_C=300A$ $V_{CE}=600V$ $V_{GE}=\pm 15V$ $R_G=1.8\Omega$ $T_{vj}=25^{\circ}C$		143		ns	
Rise Time	t_r				32		ns
Turn-off Delay Time	$t_{d(off)}$				406		ns
Fall Time	t_f				97		ns
Energy Dissipation During Turn-on Time	E_{on}				13.4		mJ
Energy Dissipation During Turn-off Time	E_{off}				14.7		mJ
Turn-on Delay Time	$t_{d(on)}$	$I_C=300A$ $V_{CE}=600V$ $V_{GE}=\pm 15V$ $R_G=1.8\Omega$ $T_{vj}=125^{\circ}C$		167		ns	
Rise Time	t_r				39		ns
Turn-off Delay Time	$t_{d(off)}$				463		ns
Fall Time	t_f				154		ns
Energy Dissipation During Turn-on Time	E_{on}				19.2		mJ
Energy Dissipation During Turn-off Time	E_{off}				22.4		mJ
SC Data	I_{sc}	$T_p \leq 10\mu s, V_{GE}=15V,$ $T_{vj}=150^{\circ}C, V_{cc}=600V,$ $V_{CEM} \leq 1200V$		1400		A	



● Diode

Absolute Maximum Ratings

Parameter	Symbol	Conditions	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	$T_{vj}=25^{\circ}C$	1200	V
Continuous DC Forward Current	I_F		300	A
Repetitive Peak Forward Current	I_{FRM}	$t_p=1ms$	600	A

Characteristic values

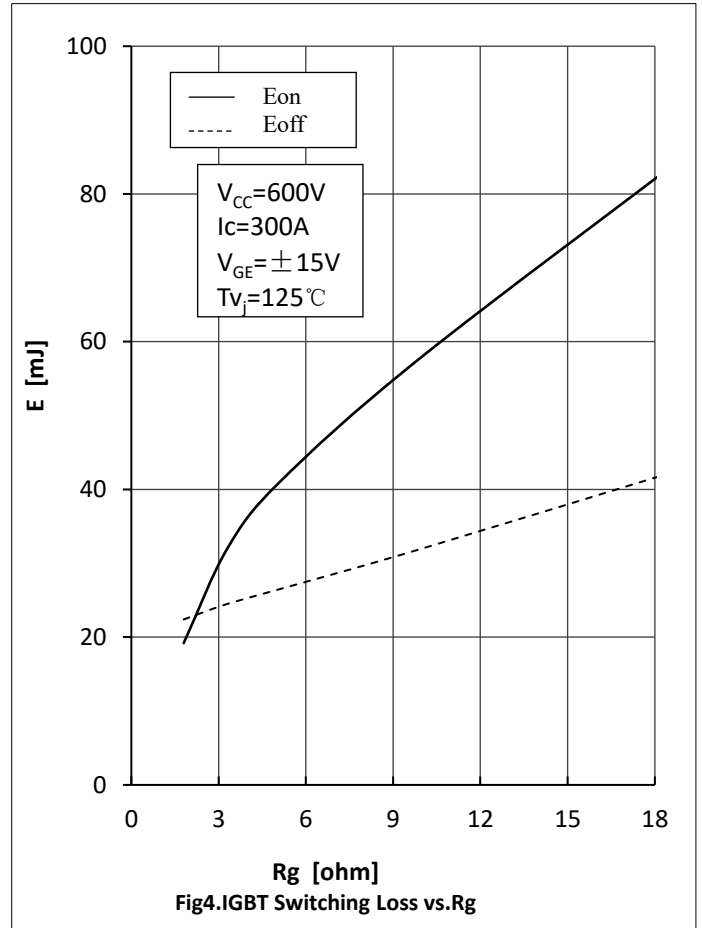
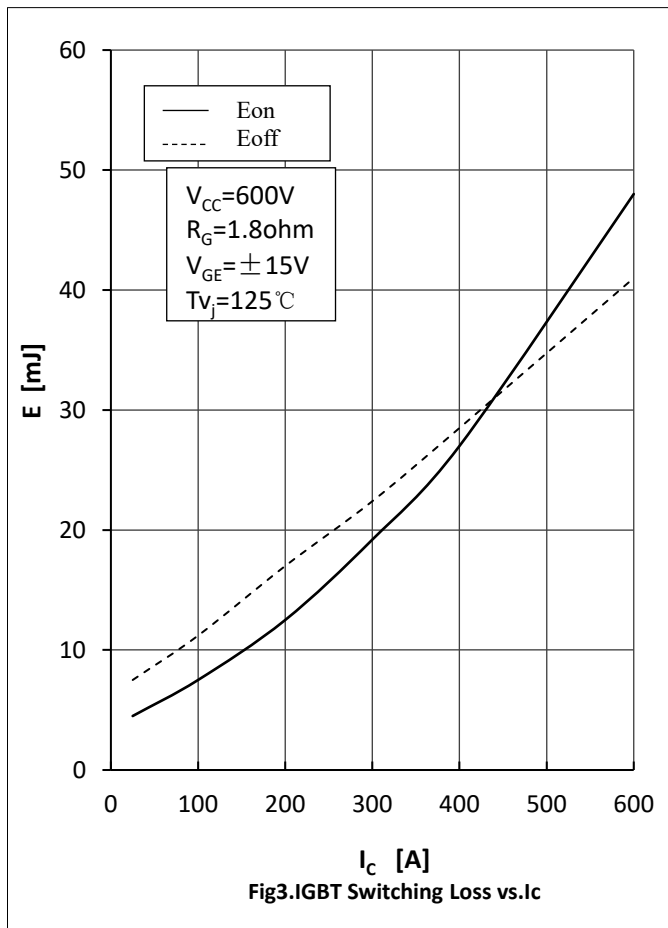
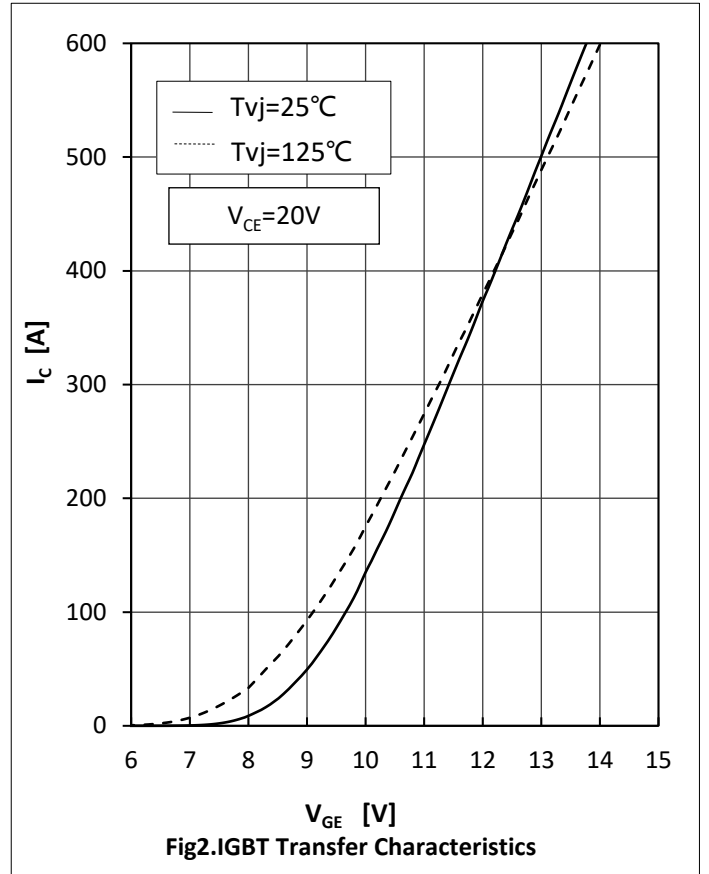
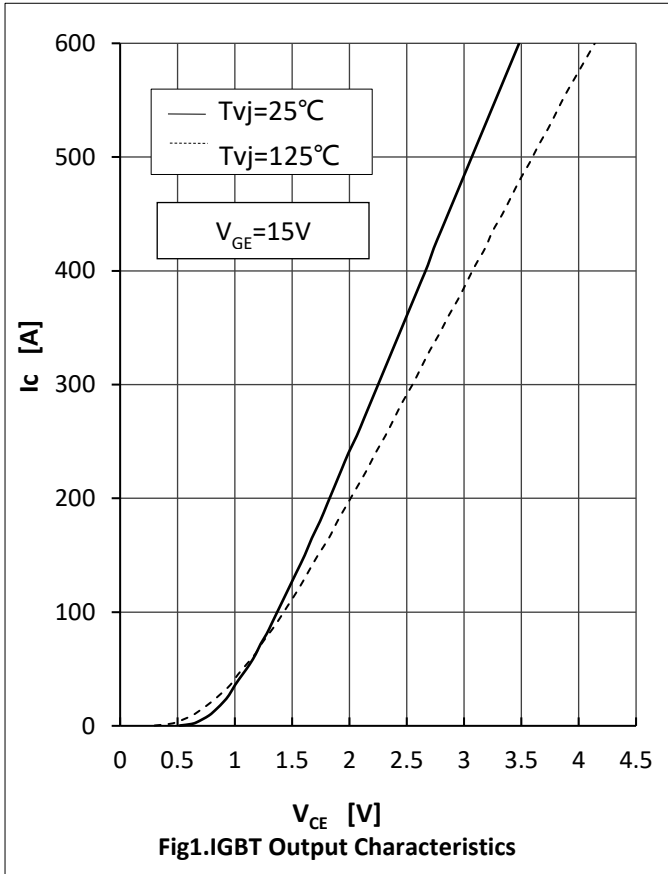
Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=300A, T_{vj}=25^{\circ}C$		2.10		V
		$I_F=300A, T_{vj}=125^{\circ}C$		2.15		
Recovered Charge	Q_{rr}	$I_F=300A$		28		μC
Peak Reverse Recovery Current	I_{rr}	$V_R=600V$ $-di_F/dt=6500A/\mu s$		355		A
Reverse Recovery Energy	E_{rec}	$T_{vj}=25^{\circ}C$		14.5		mJ
Recovered Charge	Q_{rr}	$I_F=300A$		47		μC
Peak Reverse Recovery Current	I_{rr}	$V_R=600V$ $-di_F/dt=6500A/\mu s$		394		A
Reverse Recovery Energy	E_{rec}	$T_{vj}=125^{\circ}C$		21.5		mJ

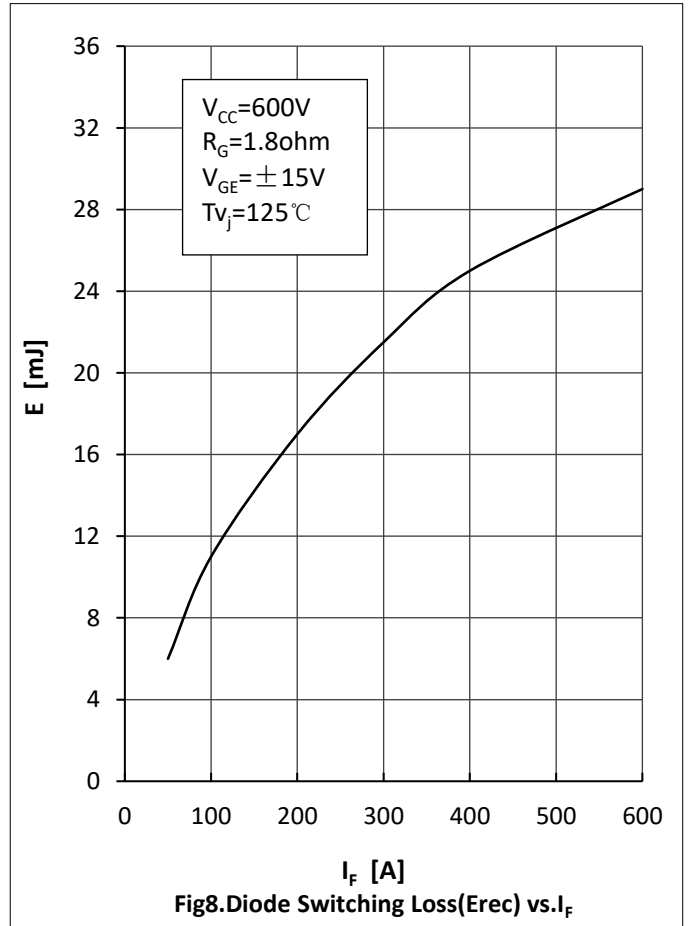
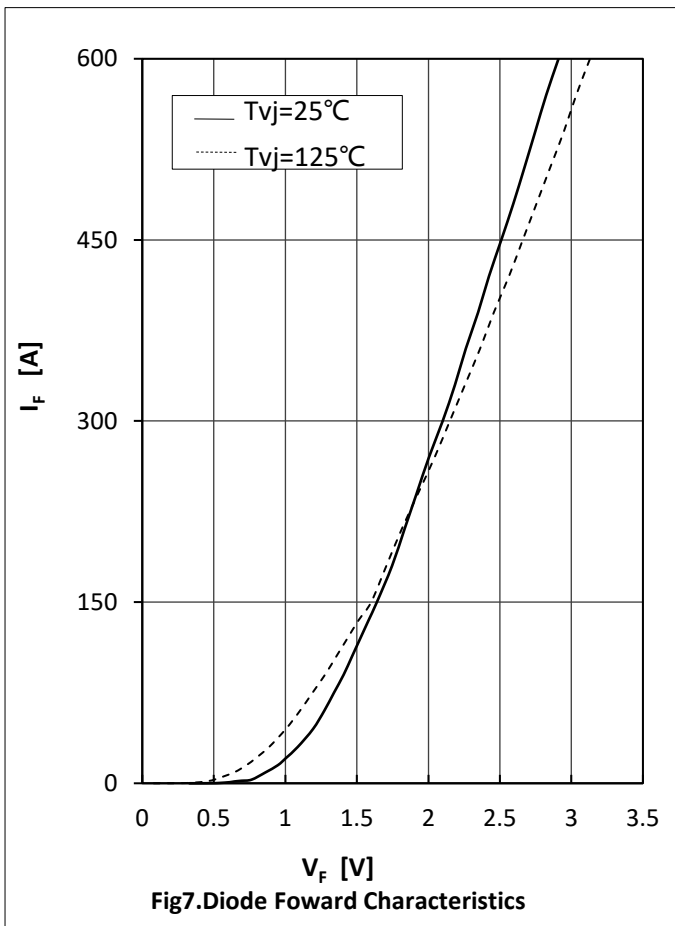
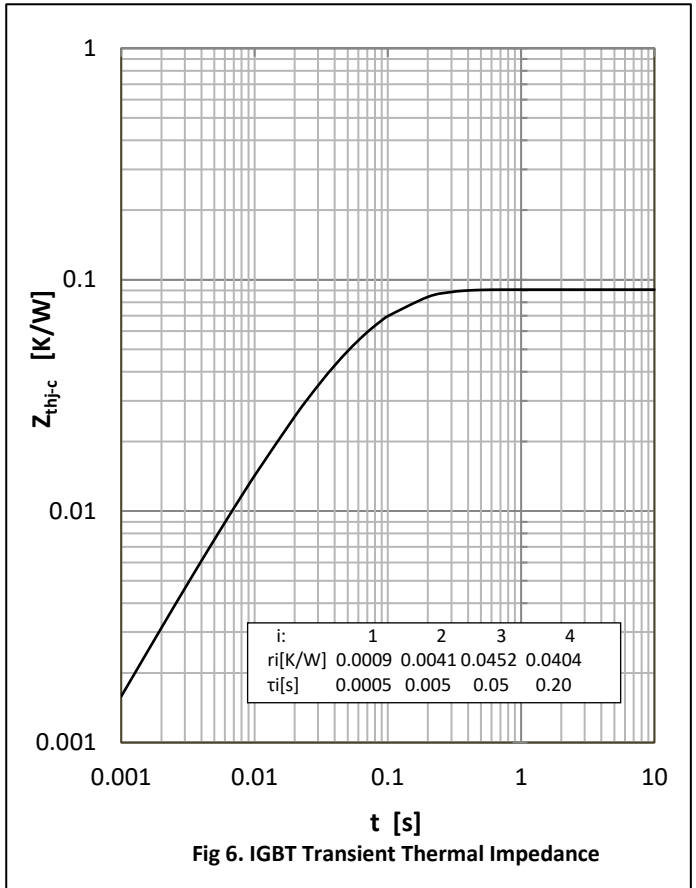
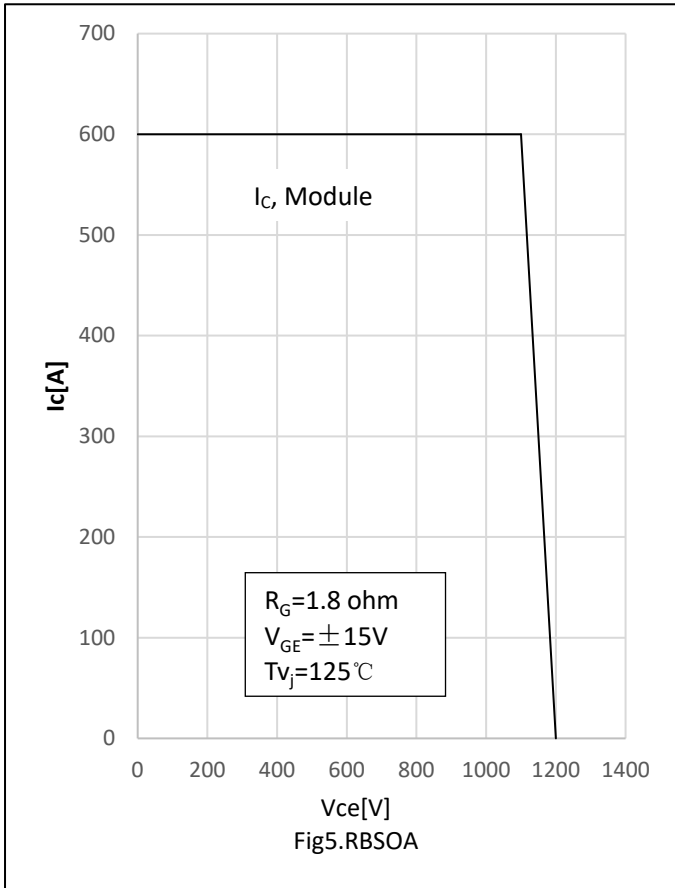


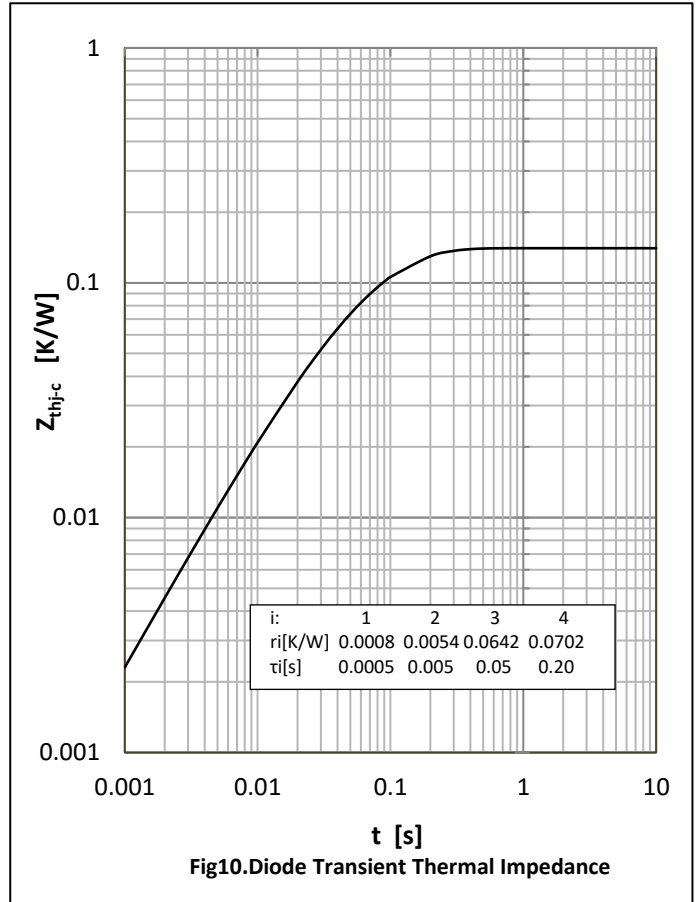
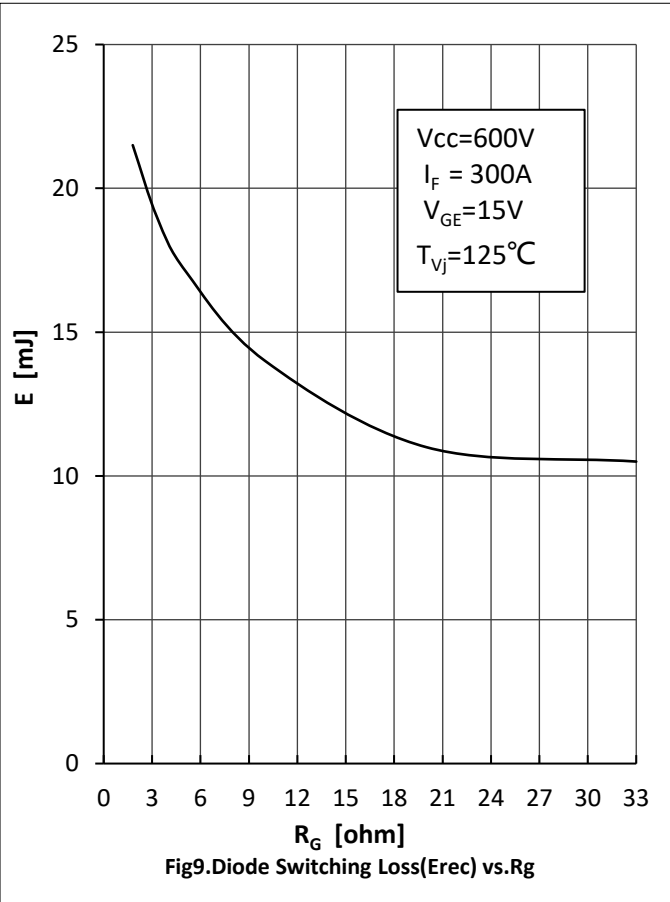
● Module Characteristics

$T_C=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Isolation voltage	V_{isol}	$t=1\text{min}, f=50\text{Hz}$	2500			V
Maximum Junction Temperature	T_{jmax}				175	$^{\circ}\text{C}$
Operating Junction Temperature	T_{vjop}		-40		150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}		-40		125	$^{\circ}\text{C}$
Thermal Resistance Junction-to Case	$R_{\theta\text{JC}}$	per IGBT			0.09	K/W
		per Diode			0.14	
Thermal Resistance Case-to Sink	$R_{\theta\text{CS}}$	Conductive grease applied		0.035		K/W
Module Electrodes Torque	M_t	Recommended(M6)	3.0		5.0	N·m
Module-to-Sink Torque	M_s	Recommended(M6)	3.0		5.0	N·m
Weight of Module	G			315		g

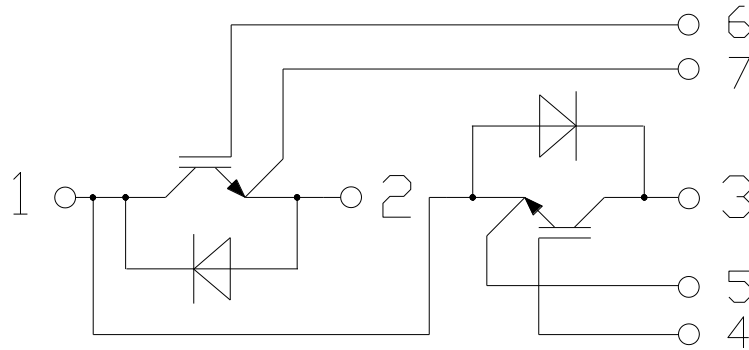








● Circuit Diagram



● Package Outline Information

Dimensions in Millimeters

